

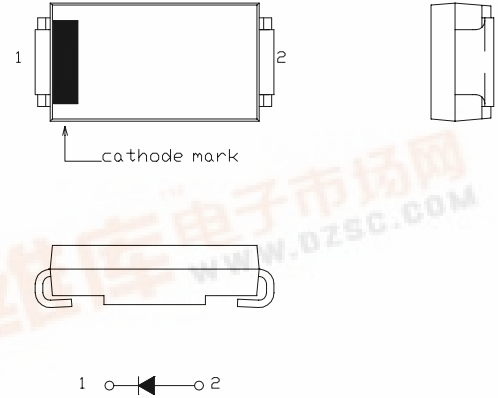


OUTLINE DRAWING

**DIODE** Type : NSD03A40

**FEATURES**

- \* **FLAT-PAK** Surface Mount Device
- \* High Surge Capability
- \* Low Forward Voltage Drop
- \* Low Reverse Leakage Current
- \* Packaged in 16mm Tape and Reel
- \* Not Rolling During Assembly



**Maximum Ratings**

Approx Net Weight:016g

Rating	Symbol	NSD03A40			Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	400			V
Average Rectified Output Current	$I_O$	1.57	$T_a=25\text{ }^\circ\text{C}$ *1	50Hz Half Sine Wave Resistive Load	A
		3.0	$T_l=108\text{ }^\circ\text{C}$ *2		
RMS Forward Current	$I_{F(RMS)}$	4.71			A
Surge Forward Current	$I_{FSM}$	80	50Hz Half Sine Wave, 1cycle Non-repetitive		A
Operating Junction Temperature Range	$T_{jw}$	-40 to +150			$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-40 to +150			$^\circ\text{C}$

**Electrical • Thermal Characteristics**

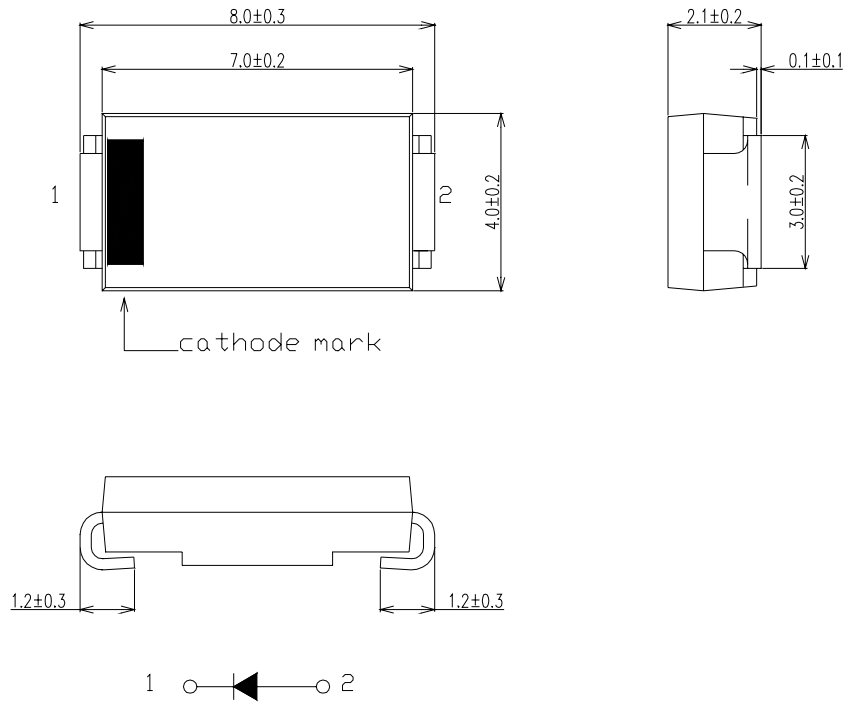
Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	$I_{RM}$	$T_j= 25^\circ\text{C}, V_{RM}= V_{RRM}$	-	-	50	$\mu\text{A}$
Peak Forward Voltage	$V_{FM}$	$T_j= 25^\circ\text{C}, I_{FM}= 3.0\text{A}$	-	-	1.0	V
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient *1	-	-	89	$^\circ\text{C} / \text{W}$
	$R_{th(j-l)}$	Junction to Lead	-	-	13	

\*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm,Both Sides)

\*2  $T_l$ = Lead Temperature



NSD03A40 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

